



DOCKET NO.: END920000149US1

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D. Small's Logan  
12/22/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Adae-Amoakoh *et al.*

Examiner: Andujar, Leonardo

Serial No.: 09/827,014

Art Unit: 2826

Filed: 4/5/01

For: **ECONOMICAL HIGH DENSITY CHIP CARRIER**

Commissioner for Patents  
Washington, D.C. 20231

RECEIVED  
DEC - 5 2002  
TC 2800 MAIL ROOM

**AMENDMENT**

Sir:

In response to the Final Office Action mailed August 28, 2002, please amend the above-identified application as follows:

**In the Specification:**

Please change the title to **ECONOMICAL HIGH DENSITY CHIP CARRIER**

**In the Technical Field:**

The Technical Field beginning on page 1, line 4 is as follows based on the amendment herein:

The invention relates generally to a high semiconductor chip package, and more particularly, to a structure for flip-chip joinable contact pads on a surface of a chip carrier.